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Details

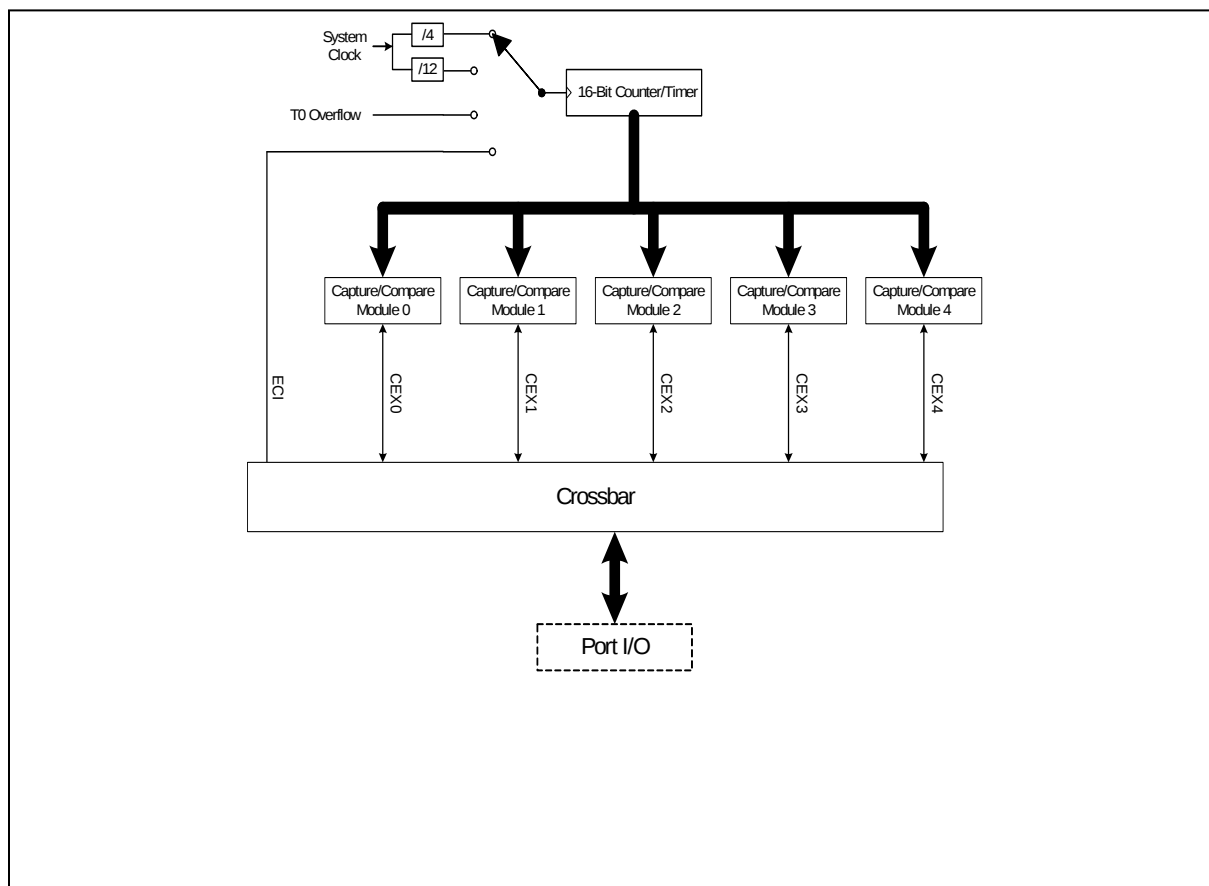
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	20MHz
Connectivity	SMBus (2-Wire/I ² C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	16
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x10b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f011r

1.5. Programmable Counter Array

The C8051F000 MCU family has an on-board Programmable Counter/Timer Array (PCA) in addition to the four 16-bit general-purpose counter/timers. The PCA consists of a dedicated 16-bit counter/timer timebase with 5 programmable capture/compare modules. The timebase gets its clock from one of four sources: the system clock divided by 12, the system clock divided by 4, Timer 0 overflow, or an External Clock Input (ECI).

Each capture/compare module can be configured to operate in one of four modes: Edge-Triggered Capture, Software Timer, High Speed Output, or Pulse Width Modulator. The PCA Capture/Compare Module I/O and External Clock Input are routed to the MCU Port I/O via the Digital Crossbar.

Figure 1.9. PCA Block Diagram



1.6. Serial Ports

The C8051F000 MCU Family includes a Full-Duplex UART, SPI Bus, and I2C/SMBus. Each of the serial buses is fully implemented in hardware and makes extensive use of the CIP-51's interrupts, thus requiring very little intervention by the CPU. The serial buses do not "share" resources such as timers, interrupts, or Port I/O, so any or all of the serial buses may be used together.

2. ABSOLUTE MAXIMUM RATINGS*

Ambient temperature under bias.....	-55 to 125°C
Storage Temperature	-65 to 150°C
Voltage on any Pin (except VDD and Port I/O) with respect to DGND	-0.3V to (VDD + 0.3V)
Voltage on any Port I/O Pin or /RST with respect to DGND.....	-0.3V to 5.8V
Voltage on VDD with respect to DGND.....	-0.3V to 4.2V
Maximum Total current through VDD, AV+, DGND and AGND.....	800mA
Maximum output current sunk by any Port pin	100mA
Maximum output current sunk by any other I/O pin	25mA
Maximum output current sourced by any Port pin	100mA
Maximum output current sourced by any other I/O pin	25mA

*Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

3. GLOBAL DC ELECTRICAL CHARACTERISTICS

-40°C to +85°C unless otherwise specified.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Analog Supply Voltage	(Note 1)	2.7	3.0	3.6	V
Analog Supply Current	Internal REF, ADC, DAC, Comparators all active		1	2	mA
Analog Supply Current with analog sub-systems inactive	Internal REF, ADC, DAC, Comparators all disabled, oscillator disabled		5	20	μA
Analog-to-Digital Supply Delta (VDD – AV+)				0.5	V
Digital Supply Voltage		2.7	3.0	3.6	V
Digital Supply Current with CPU active	VDD = 2.7V, Clock=25MHz VDD = 2.7V, Clock=1MHz VDD = 2.7V, Clock=32kHz		12.5 0.5 10		mA mA μA
Digital Supply Current (shutdown)	Oscillator not running		5		μA
Digital Supply RAM Data Retention Voltage			1.5		V
Specified Operating Temperature Range		-40		+85	°C
SYSCLK (System Clock Frequency)	C8051F005/6/7, C8051F015/6/7 (Note 2)	0		25	MHz
SYSCLK (System Clock Frequency)	C8051F000/1/2, C8051F010/1/2 (Note 2)	0		20	MHz
Tsysl (SYSCLK Low Time)		18			ns
Tsysh (SYSCLK High Time)		18			ns

Note 1: Analog Supply AV+ must be greater than 1V for VDD monitor to operate.

Note 2: SYSCLK must be at least 32 kHz to enable debugging.

Figure 5.5. AMX0SL: AMUX Channel Select Register (C8051F00x)

R/W		R/W		R/W		R/W		R/W		R/W		Reset Value
-		-		-		-		AMXAD3		AMXAD2		00000000
Bit7		Bit6		Bit5		Bit4		Bit3		Bit2		SFR Address:
												0xBB

Bits7-4: UNUSED. Read = 0000b; Write = don't care

Bits3-0: AMXAD3-0: AMUX Address Bits

0000-1111: ADC Inputs selected per chart below

		AMXAD3-0								
		0000	0001	0010	0011	0100	0101	0110	0111	1xxx
A M X 0 S L B I T S 3 - 0	0000	AIN0	AIN1	AIN2	AIN3	AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
	0001	+(AIN0) -(AIN1)		AIN2	AIN3	AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
	0010	AIN0	AIN1	+(AIN2) -(AIN3)		AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
	0011	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
	0100	AIN0	AIN1	AIN2	AIN3	+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0101	+(AIN0) -(AIN1)		AIN2	AIN3	+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0110	AIN0	AIN1	+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0111	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	1000	AIN0	AIN1	AIN2	AIN3	AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1001	+(AIN0) -(AIN1)		AIN2	AIN3	AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1010	AIN0	AIN1	+(AIN2) -(AIN3)		AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1011	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1100	AIN0	AIN1	AIN2	AIN3	+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
	1101	+(AIN0) -(AIN1)		AIN2	AIN3	+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
	1110	AIN0	AIN1	+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
	1111	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR

Figure 5.7. ADC0CN: ADC Control Register (C8051F00x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
ADCEN	ADCTM	ADCINT	ADBUSH	ADSTM1	ADSTM0	ADWINT	ADLJST	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
						(bit addressable)		0xE8
Bit7: ADCEN: ADC Enable Bit 0: ADC Disabled. ADC is in low power shutdown. 1: ADC Enabled. ADC is active and ready for data conversions. Bit6: ADCTM: ADC Track Mode Bit 0: When the ADC is enabled, tracking is always done unless a conversion is in process 1: Tracking Defined by ADSTM1-0 bits ADSTM1-0: 00: Tracking starts with the write of 1 to ADBUSH and lasts for 3 SAR clocks 01: Tracking started by the overflow of Timer 3 and last for 3 SAR clocks 10: ADC tracks only when CNVSTR input is logic low 11: Tracking started by the overflow of Timer 2 and last for 3 SAR clocks Bit5: ADCINT: ADC Conversion Complete Interrupt Flag (Must be cleared by software) 0: ADC has not completed a data conversion since the last time this flag was cleared 1: ADC has completed a data conversion Bit4: ADBUSH: ADC Busy Bit Read 0: ADC Conversion complete or no valid data has been converted since a reset. The falling edge of ADBUSH generates an interrupt when enabled. 1: ADC Busy converting data Write 0: No effect 1: Starts ADC Conversion if ADSTM1-0 = 00b Bits3-2: ADSTM1-0: ADC Start of Conversion Mode Bits 00: ADC conversion started upon every write of 1 to ADBUSH 01: ADC conversions taken on every overflow of Timer 3 10: ADC conversion started upon every rising edge of CNVSTR 11: ADC conversions taken on every overflow of Timer 2 Bit1: ADWINT: ADC Window Compare Interrupt Flag (Must be cleared by software) 0: ADC Window Comparison Data match has not occurred 1: ADC Window Comparison Data match occurred Bit0: ADLJST: ADC Left Justify Data Bit 0: Data in ADC0H:ADC0L Registers is right justified 1: Data in ADC0H:ADC0L Registers is left justified								

6.2. ADC Modes of Operation

The ADC uses VREF to determine its full-scale voltage, thus the reference must be properly configured before performing a conversion (see Section 9). The ADC has a maximum conversion speed of 100ksps. The ADC conversion clock is derived from the system clock. Conversion clock speed can be reduced by a factor of 2, 4, 8 or 16 via the ADCSC bits in the ADC0CF Register. This is useful to adjust conversion speed to accommodate different system clock speeds.

A conversion can be initiated in one of four ways, depending on the programmed states of the ADC Start of Conversion Mode bits (ADSTM1, ADSTM0) in ADC0CN. Conversions may be initiated by:

1. Writing a 1 to the ADBUSY bit of ADC0CN;
2. A Timer 3 overflow (i.e. timed continuous conversions);
3. A rising edge detected on the external ADC convert start signal, CNVSTR;
4. A Timer 2 overflow (i.e. timed continuous conversions).

Writing a 1 to ADBUSY provides software control of the ADC whereby conversions are performed “on-demand”. During conversion, the ADBUSY bit is set to 1 and restored to 0 when conversion is complete. The falling edge of ADBUSY triggers an interrupt (when enabled) and sets the ADCINT interrupt flag. **Note: When conversions are performed “on-demand”, the ADCINT flag, not ADBUSY, should be polled to determine when the conversion has completed.** Converted data is available in the ADC data word MSB and LSB registers, ADC0H, ADC0L. Converted data can be either left or right justified in the ADC0H:ADC0L register pair (see example in Figure 6.9) depending on the programmed state of the ADLJST bit in the ADC0CN register.

The ADCTM bit in register ADC0CN controls the ADC track-and-hold mode. In its default state, the ADC input is continuously tracked, except when a conversion is in progress. Setting ADCTM to 1 allows one of four different low power track-and-hold modes to be specified by states of the ADSTM1-0 bits (also in ADC0CN):

1. Tracking begins with a write of 1 to ADBUSY and lasts for 3 SAR clocks;
2. Tracking starts with an overflow of Timer 3 and lasts for 3 SAR clocks;
3. Tracking is active only when the CNVSTR input is low;
4. Tracking starts with an overflow of Timer 2 and lasts for 3 SAR clocks.

Modes 1, 2 and 4 (above) are useful when the start of conversion is triggered with a software command or when the ADC is operated continuously. Mode 3 is used when the start of conversion is triggered by external hardware. In this case, the track-and-hold is in its low power mode at times when the CNVSTR input is high. Tracking can also be disabled (shutdown) when the entire chip is in low power standby or sleep modes.

Figure 6.2. 10-Bit ADC Track and Conversion Example Timing

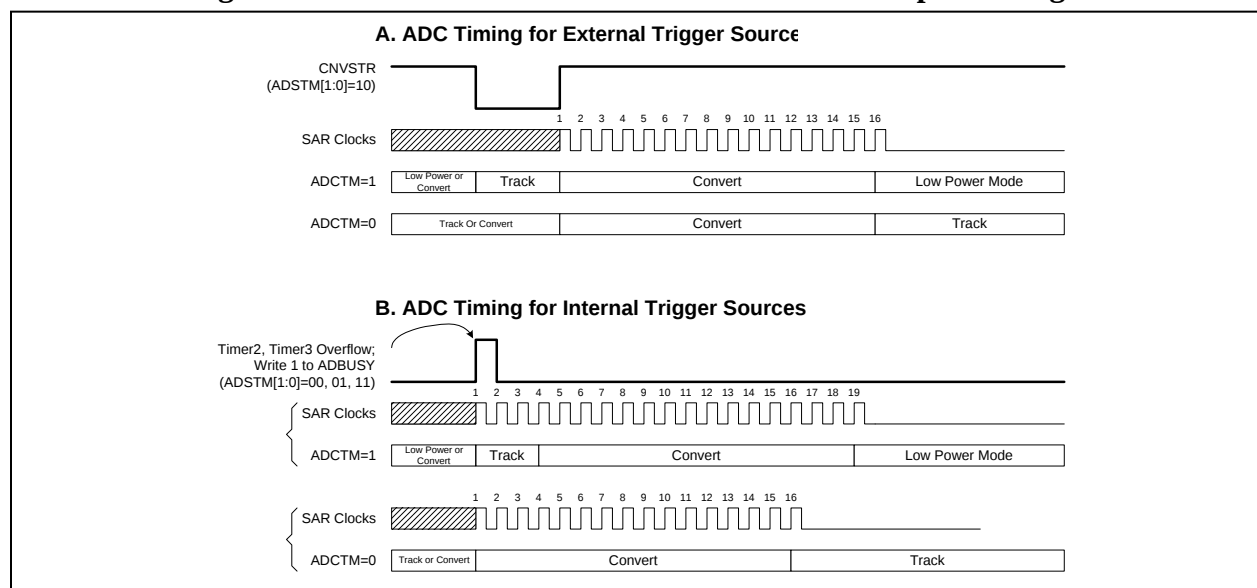


Figure 6.8. ADC0H: ADC Data Word MSB Register (C8051F01x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xBF

Bits7-0: ADC Data Word Bits
 For ADLJST = 1: Upper 8-bits of the 10-bit ADC Data Word.
 For ADLJST = 0: Bits7-2 are the sign extension of Bit1. Bits 1-0 are the upper 2-bits of the 10-bit ADC Data Word.

Figure 6.9. ADC0L: ADC Data Word LSB Register (C8051F01x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xBE

Bits7-0: ADC Data Word Bits
 For ADLJST = 1: Bits7-6 are the lower 2-bits of the 10-bit ADC Data Word. Bits5-0 will always read 0.
 For ADLJST = 0: Bits7-0 are the lower 8-bits of the 10-bit ADC Data Word.

NOTE: Resulting 10-bit ADC Data Word appears in the ADC Data Word Registers as follows:
 ADC0H[1:0]:ADC0L[7:0], if ADLJST = 0
 (ADC0H[7:2] will be sign extension of ADC0H.1 if a differential reading, otherwise = 000000b)

ADC0H[7:0]:ADC0L[7:6], if ADLJST = 1
 (ADC0L[5:0] = 000000b)

EXAMPLE: ADC Data Word Conversion Map, AIN0 Input in Single-Ended Mode
 (AMX0CF=0x00, AMX0SL=0x00)

AIN0 – AGND (Volts)	ADC0H:ADC0L (ADLJST = 0)	ADC0H:ADC0L (ADLJST = 1)
REF x (1023/1024)	0x03FF	0xFFC0
REF x 1/2	0x0200	0x8000
REF x (511/1024)	0x01FF	0x7FC0
0	0x0000	0x0000

EXAMPLE: ADC Data Word Conversion Map, AIN0-AIN1 Differential Input Pair
 (AMX0CF=0x01, AMX0SL=0x00)

AIN0 – AIN1 (Volts)	ADC0H:ADC0L (ADLJST = 0)	ADC0H:ADC0L (ADLJST = 1)
REF x (511/512)	0x01FF	0x7FC0
0	0x0000	0x0000
-REF x (1/512)	0xFFFF	0xFFC0
-REF	0xFE00	0x8000

Figure 6.15. 10-Bit ADC Window Interrupt Examples, Left Justified Data

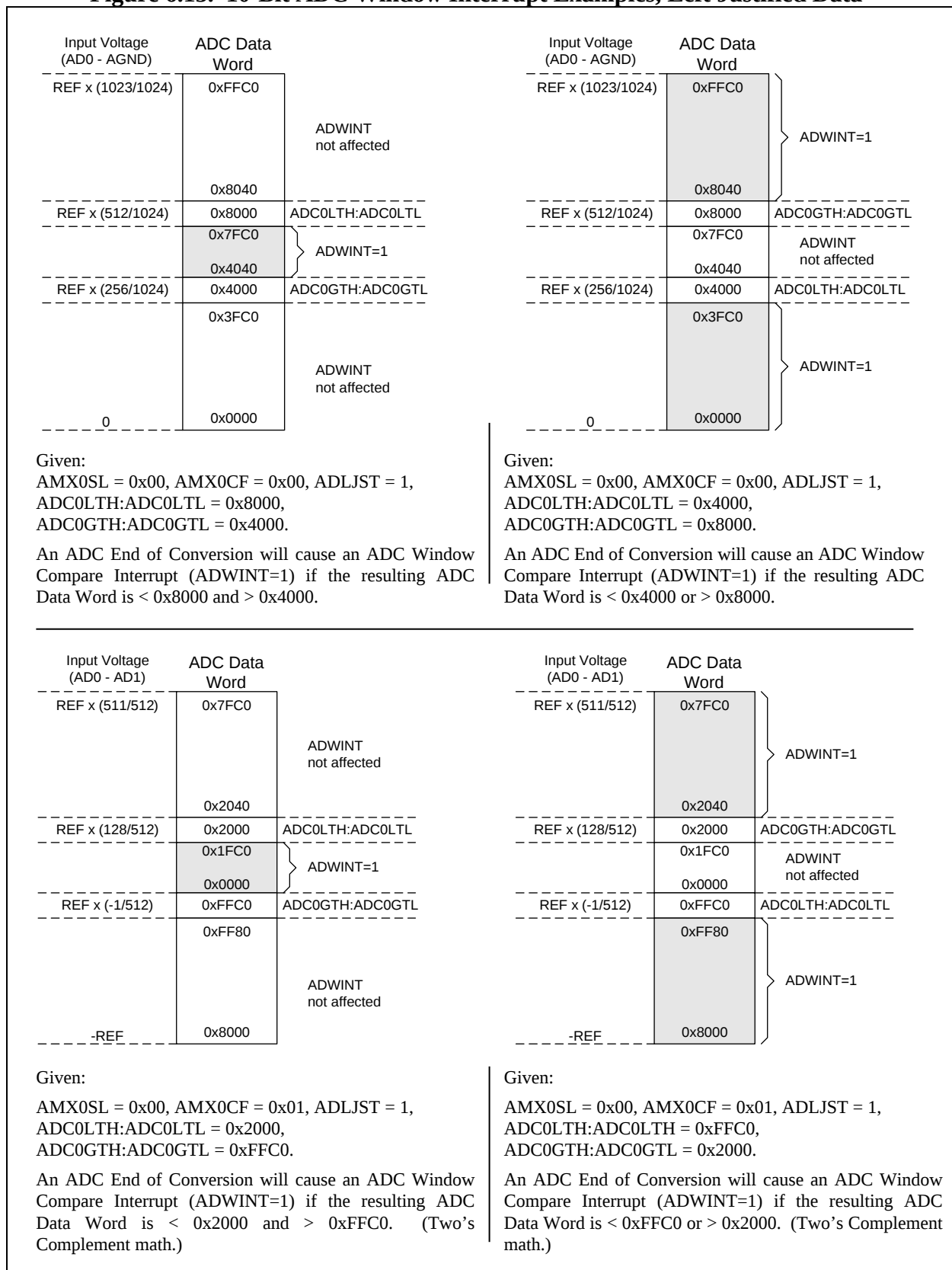


Figure 7.2. DAC0H: DAC0 High Byte Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD3

Bits7-0: DAC0 Data Word Most Significant Byte.

Figure 7.3. DAC0L: DAC0 Low Byte Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD2

Bits7-0: DAC0 Data Word Least Significant Byte.

Figure 7.4. DAC0CN: DAC0 Control Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
DAC0EN	-	-	-	-	DAC0DF2	DAC0DF1	DAC0DF0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD4

Bit7: DAC0EN: DAC0 Enable Bit
0: DAC0 Disabled. DAC0 Output pin is disabled; DAC0 is in low power shutdown mode.
1: DAC0 Enabled. DAC0 Output is pin active; DAC0 is operational.

Bits6-3: UNUSED. Read = 0000b; Write = don't care

Bits2-0: DAC0DF2-0: DAC0 Data Format Bits
000: The most significant nybble of the DAC0 Data Word is in DAC0H[3:0], while the least significant byte is in DAC0L.
001: The most significant 5-bits of the DAC0 Data Word is in DAC0H[4:0], while the least significant 7-bits is in DAC0L[7:1].
010: The most significant 6-bits of the DAC0 Data Word is in DAC0H[5:0], while the least significant 6-bits is in DAC0L[7:2].
011: The most significant 7-bits of the DAC0 Data Word is in DAC0H[6:0], while the least significant 5-bits is in DAC0L[7:3].
1xx: The most significant byte of the DAC0 Data Word is in DAC0H, while the least significant nybble is in DAC0L[7:4].

DAC0H								DAC0L							
				MSB											LSB

DAC0H								DAC0L							
				MSB										LSB	

DAC0H								DAC0L							
				MSB										LSB	

DAC0H								DAC0L							
				MSB										LSB	

Figure 7.5. DAC1H: DAC1 High Byte Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD6

Bits7-0: DAC1 Data Word Most Significant Byte.

Figure 7.6. DAC1L: DAC1 Low Byte Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD5

Bits7-0: DAC1 Data Word Least Significant Byte.

Figure 7.7. DAC1CN: DAC1 Control Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
DAC1EN	-	-	-	-	DAC1DF2	DAC1DF1	DAC1DF0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD7

Bit7: DAC1EN: DAC1 Enable Bit
 0: DAC1 Disabled. DAC1 Output pin is disabled; DAC1 is in low power shutdown mode.
 1: DAC1 Enabled. DAC1 Output is pin active; DAC1 is operational.

Bits6-3: UNUSED. Read = 0000b; Write = don't care

Bits2-0: DAC1DF2-0: DAC1 Data Format Bits
 000: The most significant nybble of the DAC1 Data Word is in DAC1H[3:0], while the least significant byte is in DAC1L.

DAC1H								DAC1L							
				MSB											LSB

001: The most significant 5-bits of the DAC1 Data Word is in DAC1H[4:0], while the least significant 7-bits is in DAC1L[7:1].

DAC1H								DAC1L							
				MSB											LSB

010: The most significant 6-bits of the DAC1 Data Word is in DAC1H[5:0], while the least significant 6-bits is in DAC1L[7:2].

DAC1H								DAC1L							
				MSB										LSB	

011: The most significant 7-bits of the DAC1 Data Word is in DAC1H[6:0], while the least significant 5-bits is in DAC1L[7:3].

DAC1H								DAC1L							
				MSB									LSB		

1xx: The most significant byte of the DAC1 Data Word is in DAC1H, while the least significant nybble is in DAC1L[7:4].

DAC1H								DAC1L							
				MSB									LSB		

Table 8.1. Comparator Electrical Characteristics

VDD = 3.0V, AV+ = 3.0V, -40°C to +85°C unless otherwise specified.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Response Time1	(CP+) – (CP-) = 100mV (Note 1)		4		μs
Response Time2	(CP+) – (CP-) = 10mV (Note 1)		12		μs
Common Mode Rejection Ratio			1.5	4	mV/V
Positive Hysteresis1	CPnHYP1-0 = 00		0	1	mV
Positive Hysteresis2	CPnHYP1-0 = 01	2	4.5	7	mV
Positive Hysteresis3	CPnHYP1-0 = 10	4	9	13	mV
Positive Hysteresis4	CPnHYP1-0 = 11	10	17	25	mV
Negative Hysteresis1	CPnHYN1-0 = 00		0	1	mV
Negative Hysteresis2	CPnHYN1-0 = 01	2	4.5	7	mV
Negative Hysteresis3	CPnHYN1-0 = 10	4	9	13	mV
Negative Hysteresis4	CPnHYN1-0 = 11	10	17	25	mV
Inverting or Non-inverting Input Voltage Range		-0.25		(AV+) + 0.25	V
Input Capacitance			7		pF
Input Bias Current		-5	0.001	+5	nA
Input Offset Voltage		-10		+10	mV
POWER SUPPLY					
Power-up Time	CPnEN from 0 to 1		20		μs
Power Supply Rejection			0.1	1	mV/V
Supply Current	Operating Mode (each comparator) at DC		1.5	10	μA

Note 1: CPnHYP1-0 = CPnHYN1-0 = 00.

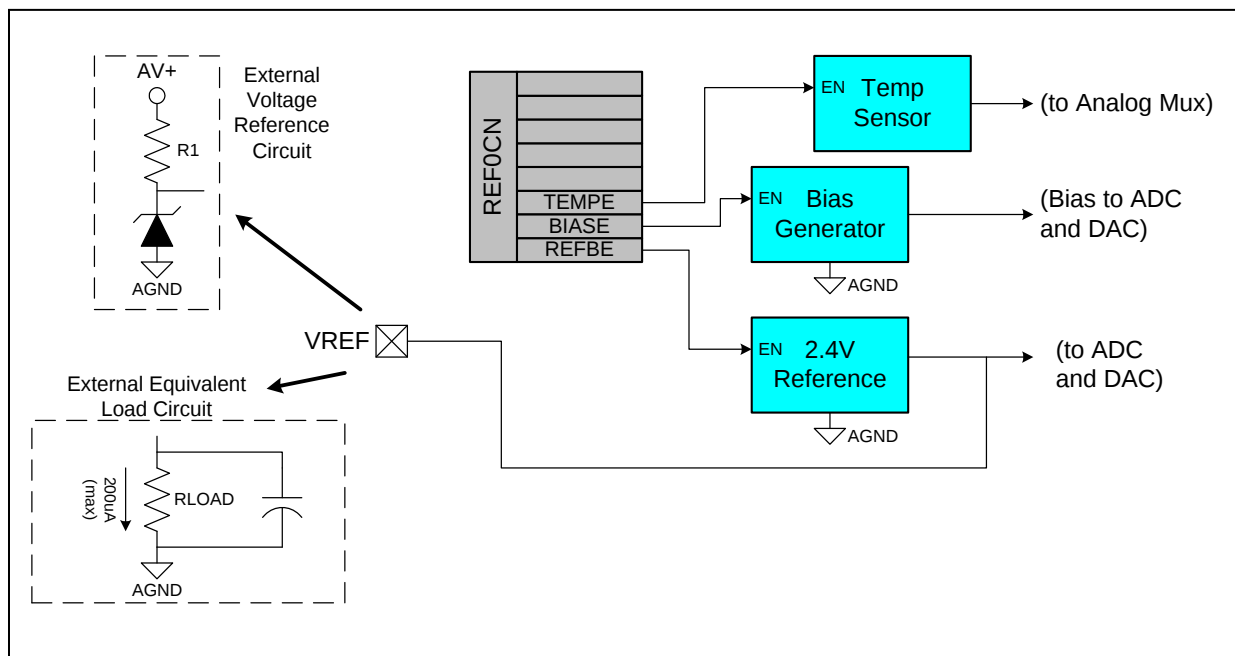
9. VOLTAGE REFERENCE

The voltage reference circuit consists of a 1.2V, 15ppm/°C (typical) bandgap voltage reference generator and a gain-of-two output buffer amplifier. The reference voltage on VREF can be connected to external devices in the system, as long as the maximum load seen by the VREF pin is less than 200μA to AGND (see Figure 9.1).

If a different reference voltage is required, an external reference can be connected to the VREF pin and the internal bandgap and buffer amplifier disabled in software. The external reference voltage must still be less than $AV+ - 0.3V$. The Reference Control Register, REF0CN (defined in Figure 9.2), provides the means to enable or disable the bandgap and buffer amplifier. The BIAS bit in REF0CN enables the bias circuitry for the ADC and DACs while the REFBE bit enables the bandgap reference and buffer amplifier which drive the VREF pin. When disabled, the supply current drawn by the bandgap and buffer amplifier falls to less than 1μA (typical) and the output of the buffer amplifier enters a high impedance state. If the internal bandgap is used as the reference voltage generator, BIAS and REFBE must both be set to 1. If an external reference is used, REFBE must be set to 0 and BIAS must be set to 1. If neither the ADC nor the DAC are being used, both of these bits can be set to 0 to conserve power. The electrical specifications for the Voltage Reference are given in Table 9.1.

The temperature sensor connects to the highest order input of the A/D converter's input multiplexer (see Figure 5.1 and Figure 5.5 for details). The TEMPE bit within REF0CN enables and disables the temperature sensor. While disabled, the temperature sensor defaults to a high impedance state and any A/D measurements performed on the sensor while disabled result in meaningless data.

Figure 9.1. Voltage Reference Functional Block Diagram



Performance

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.

With the CIP-51's maximum system clock at 25MHz, it has a peak throughput of 25MIPS. The CIP-51 has a total of 109 instructions. The number of instructions versus the system clock cycles required to execute them is as follows:

Instructions	26	50	5	14	7	3	1	2	1
Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8

Programming and Debugging Support

A JTAG-based serial interface is provided for in-system programming of the Flash program memory and communication with on-chip debug support circuitry. The reprogrammable Flash can also be read and changed a single byte at a time by the application software using the MOVC and MOVX instructions. This feature allows program memory to be used for non-volatile data storage as well as updating program code under software control.

The on-chip debug support circuitry facilitates full speed in-circuit debugging, allowing the setting of hardware breakpoints and watch points, starting, stopping and single stepping through program execution (including interrupt service routines), examination of the program's call stack, and reading/writing the contents of registers and memory. This method of on-chip debugging is completely non-intrusive and non-invasive, requiring no RAM, Stack, timers, or other on-chip resources.

The CIP-51 is supported by development tools from Silicon Laboratories and third party vendors. Silicon Labs provides an integrated development environment (IDE) including editor, macro assembler, debugger and programmer. The IDE's debugger and programmer interface to the CIP-51 via its JTAG interface to provide fast and efficient in-system device programming and debugging. Third party macro assemblers and C compilers are also available.

10.1. INSTRUCTION SET

The instruction set of the CIP-51 System Controller is fully compatible with the standard MCS-51™ instruction set. Standard 8051 development tools can be used to develop software for the CIP-51. All CIP-51 instructions are the binary and functional equivalent of their MCS-51™ counterparts, including opcodes, addressing modes and effect on PSW flags. However, instruction timing is different than that of the standard 8051.

10.1.1. Instruction and CPU Timing

In many 8051 implementations, a distinction is made between machine cycles and clock cycles, with machine cycles varying from 2 to 12 clock cycles in length. However, the CIP-51 implementation is based solely on clock cycle timing. All instruction timings are specified in terms of clock cycles.

Due to the pipelined architecture of the CIP-51, most instructions execute in the same number of clock cycles as there are program bytes in the instruction. Conditional branch instructions take one less clock cycle to complete when the branch is not taken as opposed to when the branch is taken. Table 10.1 is the CIP-51 Instruction Set Summary, which includes the mnemonic, number of bytes, and number of clock cycles for each instruction.

10.1.2. MOVX Instruction and Program Memory

The MOVX instruction is typically used to access external data memory. In the CIP-51, the MOVX instruction can access the on-chip program memory space implemented as reprogrammable Flash memory using the control bits in the PSCTL register (see Figure 11.1). This feature provides a mechanism for the CIP-51 to update program code and use the program memory space for non-volatile data storage. For the products with RAM mapped into external data memory space (C8051F005/06/07/15/16/17), MOVX is still used to read/write this memory with the PSCTL

Mnemonic	Description	Bytes	Clock Cycles
RR A	Rotate A right	1	1
RRC A	Rotate A right through carry	1	1
SWAP A	Swap nibbles of A	1	1
DATA TRANSFER			
MOV A,Rn	Move register to A	1	1
MOV A,direct	Move direct byte to A	2	2
MOV A,@Ri	Move indirect RAM to A	1	2
MOV A,#data	Move immediate to A	2	2
MOV Rn,A	Move A to register	1	1
MOV Rn,direct	Move direct byte to register	2	2
MOV Rn,#data	Move immediate to register	2	2
MOV direct,A	Move A to direct byte	2	2
MOV direct,Rn	Move register to direct byte	2	2
MOV direct,direct	Move direct byte to direct	3	3
MOV direct,@Ri	Move indirect RAM to direct byte	2	2
MOV direct,#data	Move immediate to direct byte	3	3
MOV @Ri,A	Move A to indirect RAM	1	2
MOV @Ri,direct	Move direct byte to indirect RAM	2	2
MOV @Ri,#data	Move immediate to indirect RAM	2	2
MOV DPTR,#data16	Load data pointer with 16-bit constant	3	3
MOVC A,@A+DPTR	Move code byte relative DPTR to A	1	3
MOVC A,@A+PC	Move code byte relative PC to A	1	3
MOVX A,@Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri,A	Move A to external data (8-bit address)	1	3
MOVX A,@DPTR	Move external data (16-bit address) to A	1	3
MOVX @DPTR,A	Move A to external data (16-bit address)	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A,Rn	Exchange register with A	1	1
XCH A,direct	Exchange direct byte with A	2	2
XCH A,@Ri	Exchange indirect RAM with A	1	2
XCHD A,@Ri	Exchange low nibble of indirect RAM with A	1	2
BOOLEAN MANIPULATION			
CLR C	Clear carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement carry	1	1
CPL bit	Complement direct bit	2	2
ANL C,bit	AND direct bit to carry	2	2
ANL C,/bit	AND complement of direct bit to carry	2	2
ORL C,bit	OR direct bit to carry	2	2
ORL C,/bit	OR complement of direct bit to carry	2	2
MOV C,bit	Move direct bit to carry	2	2
MOV bit,C	Move carry to direct bit	2	2
JC rel	Jump if carry is set	2	2/3
JNC rel	Jump if carry not set	2	2/3
JB bit,rel	Jump if direct bit is set	3	3/4
JNB bit,rel	Jump if direct bit is not set	3	3/4
JBC bit,rel	Jump if direct bit is set and clear bit	3	3/4

13.4. External Reset

The external /RST pin provides a means for external circuitry to force the MCU into a reset state. Asserting an active-low signal on the /RST pin will cause the MCU to enter the reset state. Although there is a weak internal pullup, it may be desirable to provide an external pull-up and/or decoupling of the /RST pin to avoid erroneous noise-induced resets. The MCU will remain in reset until at least 12 clock cycles after the active-low /RST signal is removed. The PINRSF flag (RSTSRC.0) is set on exit from an external reset. The /RST pin is also 5V tolerant.

13.5. Missing Clock Detector Reset

The Missing Clock Detector is essentially a one-shot circuit that is triggered by the MCU system clock. If the system clock goes away for more than 100 μ s, the one-shot will time out and generate a reset. After a Missing Clock Detector reset, the MCDRSF flag (RSTSRC.2) will be set, signifying the MSD as the reset source; otherwise, this bit reads 0. The state of the /RST pin is unaffected by this reset. Setting the MSCLKE bit in the OSCICN register (see Figure 14.2) enables the Missing Clock Detector.

13.6. Comparator 0 Reset

Comparator 0 can be configured as an active-low reset input by writing a 1 to the CORSEF flag (RSTSRC.5). Comparator 0 should be enabled using CPT0CN.7 (see Figure 8.3) at least 20 μ s prior to writing to CORSEF to prevent any turn-on chatter on the output from generating an unwanted reset. When configured as a reset, if the non-inverting input voltage (on CP0+) is less than the inverting input voltage (on CP0-), the MCU is put into the reset state. After a Comparator 0 Reset, the CORSEF flag (RSTSRC.5) will read 1 signifying Comparator 0 as the reset source; otherwise, this bit reads 0. The state of the /RST pin is unaffected by this reset. Also, Comparator 0 can generate a reset with or without the system clock.

13.7. External CNVSTR Pin Reset

The external CNVSTR signal can be configured as an active-low reset input by writing a 1 to the CNVRSEF flag (RSTSRC.6). The CNVSTR signal can appear on any of the P0, P1, or P2 I/O pins as described in Section 15.1. (Note that the Crossbar must be configured for the CNVSTR signal to be routed to the appropriate Port I/O.) The Crossbar should be configured and enabled before the CNVRSEF is set to configure CNVSTR as a reset source. When configured as a reset, CNVSTR is active-low and level sensitive. After a CNVSTR reset, the CNVRSEF flag (RSTSRC.6) will read 1 signifying CNVSTR as the reset source; otherwise, this bit reads 0. The state of the /RST pin is unaffected by this reset.

13.8. Watchdog Timer Reset

The MCU includes a programmable Watchdog Timer (WDT) running off the system clock. The WDT will force the MCU into the reset state when the watchdog timer overflows. To prevent the reset, the WDT must be restarted by application software before the overflow occurs. If the system experiences a software/hardware malfunction preventing the software from restarting the WDT, the WDT will overflow and cause a reset. This should prevent the system from running out of control.

The WDT is automatically enabled and started with the default maximum time interval on exit from all resets. If desired the WDT can be disabled by system software or locked on to prevent accidental disabling. Once locked, the WDT cannot be disabled until the next system reset. The state of the /RST pin is unaffected by this reset.

Figure 15.11. P2: Port2 Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
P2.7	P2.6	P2.5	P2.4	P2.3	P2.2	P2.1	P2.0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Address: 0xA0

Bits7-0: P2.[7:0]
 (Write – Output appears on I/O pins per XBR0, XBR1, and XBR2 registers)
 0: Logic Low Output.
 1: Logic High Output (high-impedance if corresponding PRT2CF.n bit = 0)
 (Read – Regardless of XBR0, XBR1, and XBR2 Register settings).
 0: P2.n is logic low.
 1: P2.n is logic high.

Figure 15.12. PRT2CF: Port2 Configuration Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xA6

Bits7-0: PRT2CF.[7:0]: Output Configuration Bits for P2.7-P2.0 (respectively)
 0: Corresponding P2.n Output mode is Open-Drain.
 1: Corresponding P2.n Output mode is Push-Pull.

Figure 15.13. P3: Port3 Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
P3.7	P3.6	P3.5	P3.4	P3.3	P3.2	P3.1	P3.0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
							(bit addressable)	0xB0

Bits7-0: P3.[7:0]
 (Write)
 0: Logic Low Output.
 1: Logic High Output (high-impedance if corresponding PRT3CF.n bit = 0)
 (Read)
 0: P3.n is logic low.
 1: P3.n is logic high.

Figure 15.14. PRT3CF: Port3 Configuration Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xA7

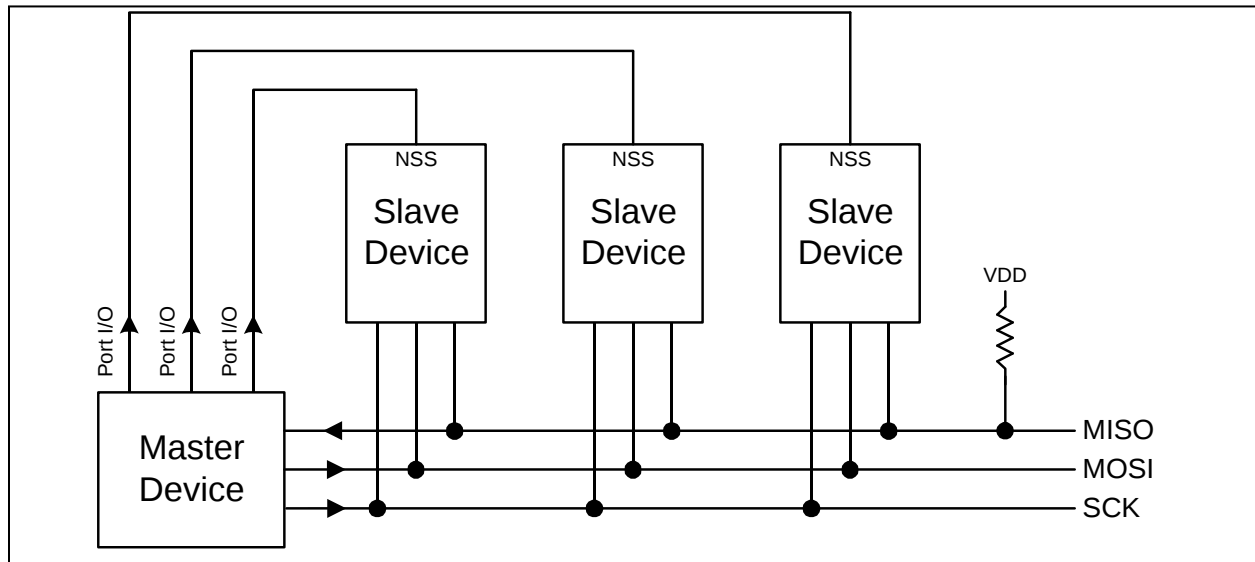
Bits7-0: PRT3CF.[7:0]: Output Configuration Bits for P3.7-P3.0 (respectively)
 0: Corresponding P3.n Output mode is Open-Drain.
 1: Corresponding P3.n Output mode is Push-Pull.

Table 15.2. Port I/O DC Electrical Characteristics

VDD = 2.7 to 3.6V, -40°C to +85°C unless otherwise specified.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Output High Voltage	I _{OH} = -10uA, Port I/O push-pull I _{OH} = -3mA, Port I/O push-pull I _{OH} = -10mA, Port I/O push-pull	VDD – 0.1 VDD – 0.7	VDD – 0.8		V
Output Low Voltage	I _{OL} = 10uA I _{OL} = 8.5mA I _{OL} = 25mA		1.0	0.1 0.6	V
Input High Voltage		0.7 x VDD			V
Input Low Voltage				0.3 x VDD	V
Input Leakage Current	DGND < Port Pin < VDD, Pin Tri-state Weak Pull-up Off Weak Pull-up On		30	±1	μA
Capacitive Loading			5		pF

Figure 17.2. Typical SPI Interconnection



17.1. Signal Descriptions

The four signals used by the SPI (MOSI, MISO, SCK, NSS) are described below.

17.1.1. Master Out, Slave In

The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. Data is transferred most-significant bit first.

17.1.2. Master In, Slave Out

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. Data is transferred most-significant bit first. A SPI slave places the MISO pin in a high-impedance state when the slave is not selected.

17.1.3. Serial Clock

The serial clock (SCK) signal is an output from the master device and an input to slave devices. It is used to synchronize the transfer of data between the master and slave on the MOSI and MISO lines.

17.1.4. Slave Select

The slave select (NSS) signal is an input used to select the SPI module when in slave mode by a master, or to disable the SPI module when in master mode. When in slave mode, it is pulled low to initiate a data transfer and remains low for the duration of the transfer.

Figure 19.5. TMOD: Timer Mode Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
GATE1	C/T1	T1M1	T1M0	GATE0	C/T0	T0M1	T0M0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0x89

Bit7: GATE1: Timer 1 Gate Control.
0: Timer 1 enabled when TR1 = 1 irrespective of /INT1 logic level.
1: Timer 1 enabled only when TR1 = 1 AND /INT1 = logic level one.

Bit6: C/T1: Counter/Timer 1 Select.
0: Timer Function: Timer 1 incremented by clock defined by T1M bit (CKCON.4).
1: Counter Function: Timer 1 incremented by high-to-low transitions on external input pin (T1).

Bits5-4: T1M1-T1M0: Timer 1 Mode Select.
These bits select the Timer 1 operation mode.

T1M1	T1M0	Mode
0	0	Mode 0: 13-bit counter/timer
0	1	Mode 1: 16-bit counter/timer
1	0	Mode 2: 8-bit counter/timer with auto-reload
1	1	Mode 3: Timer 1 Inactive/stopped

Bit3: GATE0: Timer 0 Gate Control.
0: Timer 0 enabled when TR0 = 1 irrespective of /INT0 logic level.
1: Timer 0 enabled only when TR0 = 1 AND /INT0 = logic level one.

Bit2: C/T0: Counter/Timer Select.
0: Timer Function: Timer 0 incremented by clock defined by T0M bit (CKCON.3).
1: Counter Function: Timer 0 incremented by high-to-low transitions on external input pin (T0).

Bits1-0: T0M1-T0M0: Timer 0 Mode Select.
These bits select the Timer 0 operation mode.

T0M1	T0M0	Mode
0	0	Mode 0: 13-bit counter/timer
0	1	Mode 1: 16-bit counter/timer
1	0	Mode 2: 8-bit counter/timer with auto-reload
1	1	Mode 3: Two 8-bit counter/timers

21.1. Boundary Scan

The Data Register in the Boundary Scan path is an 87-bit shift register. The Boundary DR provides control and observability of all the device pins as well as the SFR bus and Weak Pullup feature via the EXTEST and SAMPLE commands.

Table 21.1. Boundary Data Register Bit Definitions

EXTEST provides access to both capture and update actions, while Sample only performs a capture.

Bit	Action	Target
0	Capture	Reset Enable from MCU
	Update	Reset Enable to /RST pin
1	Capture	Reset input from /RST pin
	Update	Reset output to /RST pin
2	Capture	External Clock from XTAL1 pin
	Update	Not used
3	Capture	Weak pullup enable from MCU
	Update	Weak pullup enable to Port Pins
4-11	Capture	SFR Address Bus bit from CIP-51 (e.g. Bit4=SFRA0, Bit5=SFRA1...)
	Update	SFR Address Bus bit to SFR Address Bus (e.g. Bit4=XSFA0, Bit5=XSFA1)
12-19	Capture	SFR Data Bus bit read from SFR (e.g. Bit12=SFRD0, Bit13=SFRD1...)
	Update	SFR Data Bus bit written to SFR (e.g. Bit12=SFRD0, Bit13=SFRD1...)
20	Capture	SFR Write Strobe from CIP-51
	Update	SFR Write Strobe to SFR Bus
21	Capture	SFR Read Strobe from CIP-51
	Update	SFR Read Strobe to SFR Bus
22	Capture	SFR Read/Modify/Write Strobe from CIP-51
	Update	SFR Read/Modify/Write Strobe to SFR Bus
23,25,27,29, 31,33,35,37	Capture	P0.n output enable from MCU (e.g. Bit23=P0.0, Bit25=P0.1, etc.)
	Update	P0.n output enable to pin (e.g. Bit23=P0.0oe, Bit25=P0.1oe, etc.)
24,26,28,30, 32,34,36,38	Capture	P0.n input from pin (e.g. Bit24=P0.0, Bit26=P0.1, etc.)
	Update	P0.n output to pin (e.g. Bit24=P0.0, Bit26=P0.1, etc.)
39,41,43,45, 47,49,51,53	Capture	P1.n output enable from MCU (e.g. Bit39=P1.0, Bit41=P1.1, etc.)
	Update	P1.n output enable to pin (e.g. Bit39=P1.0oe, Bit41=P1.1oe, etc.)
40,42,44,46, 48,50,52,54	Capture	P1.n input from pin (e.g. Bit40=P1.0, Bit42=P1.1, etc.)
	Update	P1.n output to pin (e.g. Bit40=P1.0, Bit42=P1.1, etc.)
55,57,59,61, 63,65,67,69	Capture	P2.n output enable from MCU (e.g. Bit55=P2.0, Bit57=P2.1, etc.)
	Update	P2.n output enable to pin (e.g. Bit55=P2.0oe, Bit57=P2.1oe, etc.)
56,58,60,62, 64,66,68,70	Capture	P2.n input from pin (e.g. Bit56=P2.0, Bit58=P2.1, etc.)
	Update	P2.n output to pin (e.g. Bit56=P2.0, Bit58=P2.1, etc.)
71,73,75,77, 79,81,83,85	Capture	P3.n output enable from MCU (e.g. Bit71=P3.0, Bit73=P3.1, etc.)
	Update	P3.n output enable to pin (e.g. Bit71=P3.0oe, Bit73=P3.1oe, etc.)
72,74,76,78, 80,82,84,86	Capture	P3.n input from pin (e.g. Bit72=P3.0, Bit74=P3.1, etc.)
	Update	P3.n output to pin (e.g. Bit72=P3.0, Bit74=P3.1, etc.)

Figure 21.3. FLASHCON: JTAG Flash Control Register

WRMD3	WRMD2	WRMD1	WRMD0	RDMD3	RDMD2	RDMD1	RDMD0	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	00000000

This register determines how the Flash interface logic will respond to reads and writes to the FLASHDAT Register.

Bits7-4: WRMD3-0: Write Mode Select Bits.
The Write Mode Select Bits control how the interface logic responds to writes to the FLASHDAT Register per the following values:
0000: A FLASHDAT write replaces the data in the FLASHDAT register, but is otherwise ignored.
0001: A FLASHDAT write initiates a write of FLASHDAT into the memory location addressed by the FLASHADR register. FLASHADR is incremented by one when complete.
0010: A FLASHDAT write initiates an erasure (sets all bytes to 0xFF) of the Flash page containing the address in FLASHADR. FLASHDAT must be 0xA5 for the erase to occur. FLASHADR is not affected. If FLASHADR = 0x7DFE – 0x7DFF, the entire user space will be erased (i.e. entire Flash memory except for Reserved area 0x7E00 – 0x7FFF).
(All other values for WRMD3-0 are reserved.)

Bits3-0: RDMD3-0: Read Mode Select Bits.
The Read Mode Select Bits control how the interface logic responds to reads to the FLASHDAT Register per the following values:
0000: A FLASHDAT read provides the data in the FLASHDAT register, but is otherwise ignored.
0001: A FLASHDAT read initiates a read of the byte addressed by the FLASHADR register if no operation is currently active. This mode is used for block reads.
0010: A FLASHDAT read initiates a read of the byte addressed by FLASHADR only if no operation is active and any data from a previous read has already been read from FLASHDAT. This mode allows single bytes to be read (or the last byte of a block) without initiating an extra read.
(All other values for RDMD3-0 are reserved.)

Figure 21.4. FLASHADR: JTAG Flash Address Register

																Reset Value
Bit15															Bit0	0x0000

This register holds the address for all JTAG Flash read, write, and erase operations. This register autoincrements after each read or write, regardless of whether the operation succeeded or failed.

Bits15-0: Flash Operation 16-bit Address.